



SLOVENSKI STANDARD

SIST EN 62047-22:2014

01-november-2014

Polprevodniški elementi - Mikroelektromehanski elementi - 22. del: Metoda elektromehanskega nateznega preskušanja prevodnih tankih plasti na upogljivih podlagah (IEC 62047-22:2014)

Semiconductor devices - Micro-electromechanical devices - Part 22: Electromechanical tensile test method for conductive thin films on flexible substrates

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Dispositifs a semiconducteurs - Dispositifs microélectromécaniques - Partie 22: Méthode d'essai de traction électromécanique pour les couches minces conductrices sur des substrats souples

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Ta slovenski standard je istoveten z: EN 62047-22:2014

ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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EUROPEAN STANDARD

EN 62047-22

NORME EUROPÉENNE

EUROPÄISCHE NORM

September 2014

ICS 01.080.99

English Version

**Semiconductor devices - Micro-electromechanical devices -
Part 22: Electromechanical tensile test method for conductive
thin films on flexible substrates
(IEC 62047-22:2014)**

Dispositifs à semiconducteurs - Dispositifs
microélectromécaniques -
Partie 22: Méthode d'essai de traction électromécanique
pour les couches minces conductrices sur des substrats
souples
(CEI 62047-22:2014)

Halbleiterbauelemente - Bauelemente der
Mikrosystemtechnik -
Teil 22: Elektromechanisches Zug-Prüfverfahren für
leitfähige Dünnschichten auf flexiblen Substraten
(IEC 62047-22:2014)

This European Standard was approved by CENELEC on 2014-07-24. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

Foreword

The text of document 47F/186/FDIS, future edition 1 of IEC 62047-22, prepared by SC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-22:2014.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2015-04-24
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2017-07-24

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-2	2006	Semiconductor devices - Micro-electromechanical devices - Part 2: Tensile testing method of thin film materials	EN 62047-2	2006
IEC 62047-3	2006	Semiconductor devices - Micro-electromechanical devices - Part 3: Thin film standard test piece for tensile testing	EN 62047-3	2006
IEC 62047-8	2011	Semiconductor devices - Micro-electromechanical devices - Part 8: Strip bending test method for tensile property measurement of thin films	EN 62047-8	2011
ISO 527-3	1995	Plastics - Determination of tensile properties - Part-3: Test conditions for films and sheets	EN ISO 527-3	1995

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Edition 1.0 2014-06

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Semiconductor devices – Micro-electromechanical devices –
Part 22: Electromechanical tensile test method for conductive thin films on
flexible substrates**

**Dispositifs à semiconducteurs – Dispositifs microélectromécaniques –
Partie 22: Méthode d'essai de traction électromécanique pour les couches
minces conductrices sur des substrats souples**

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COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –**

**Part 22: Electromechanical tensile test method
for conductive thin films on flexible substrates**

FOREWORD

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International Standard IEC 62047-22 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/186/FDIS	47F/190/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.